

**Product / Package Information**

Package	LQFP
Lead Count	44
Body Size	10 X 10 X 1.4
Terminal Finish	100 Sn

**Environmental Information**

RoHS Compliant	Yes
High Temperature Compliant	Yes
Halogen Free Compliant	Yes
REACH SVHC Compliant	Yes

**Materials Declaration**

**Molding Compound**

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Other inorganic materials	Silica	60676-86-0	2.20 E-01	86.91	869100	64.23	642285
Thermosets	Epoxy and Phenol resin	Proprietary	3.24 E-02	12.78	127800	9.44	94447
Other inorganic materials	Carbon black	1333-86-4	7.86 E-04	0.31	3100	0.23	2291
Subtotal			2.54 E-01	100	1000000	73.90	739023

**Leadframe**

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Copper & its alloys	Copper	7440-50-8	7.24 E-02	97.50	975000	21.10	211003
Copper & its alloys	Iron	7439-89-6	1.75 E-03	2.35	23500	0.51	5086
Copper & its alloys	Zinc	7440-66-6	8.91 E-05	0.12	1200	0.03	260
Copper & its alloys	Phosphorus	7723-14-0	2.23 E-05	0.03	300	0.01	65
Subtotal			7.43 E-02	100.00	1000000	21.64	216413

**Internal Leadframe Plating**

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Precious metals	Silver	7440-22-4	7.35 E-04	100	1000000	0.21	2142

**External Leadframe Plating**

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Tin & its alloys	Tin	7440-31-5	5.71 E-03	100	1000000	1.66	16633

**Bond Wires**

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Precious Metals	Gold	7440-57-5	1.14 E-03	99	990000	0.33	3326
Precious Metals	Palladium	7440-05-3	1.15 E-05	1	10000	0.003	34
Subtotal			1.15E-03	100	1000000	0.34	3360

**Chip**

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Other inorganic materials	Doped Silicon	7440-21-3	6.37 E-03	100	1000000	1.86	18562

**Die Attach**

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Precious metals	Silver	7440-22-4	9.76 E-04	73.54	735400	0.28	2844
Other organic materials	Epoxy resin A	TS ref# 10013	9.75 E-05	7.35	73500	0.03	284
Others	Anhydride	TS ref# 10181	9.75 E-05	7.35	73500	0.03	284
Other organic materials	2,6-Diglycidyl phenyl allyl ether oligomer	Unassigned	3.90 E-05	2.94	29400	0.01	114
Other organic materials	Epoxy resin B	TS ref# 10237	3.90 E-05	2.94	29400	0.01	114
Others	Epoxy resin modifier	TS ref# 10038	3.90 E-05	2.94	29400	0.01	114
Others	Anhydride	TS ref# 10180	3.90 E-05	2.94	29400	0.01	114
Subtotal			1.33 E-03	100.00	1000000	0.39	3867

<b>Package Totals</b>			<b>Weight (g)</b> 3.43 E-01			<b>Percentage (%)</b> 100.00	<b>PPM</b> 1000000
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Note: The information provided in this declaration are true to the best of ADI's knowledge. ADI derived most of the information listed in this declaration from documents provided by third parties, and assumes no liability to any inaccuracy of such information.



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